Ver.1.00

TEMPORARY SPECIFICATION

POWER INDUCTOR

NRS6010 Series

Taiyo Yuden reserves the right to make change to the Temporary Specification at any time without notice.

TAIYO YUDEN

		Specifications		No.		
		NRS6010 T)	/PE	(1/12)		
1.	 Range of application This specifications are applied to Power Inductor, NRS6010 type. 					
2.	Ordering code Ex Standard meas	mple : <u>NRS</u> <u>6010</u> (1) (2) ((1) Type (2) External dimensions (3) Packing style (T: Tape & (4) Inductance (5) Inductance tolerance (6) Internal Code	<u>T 100 M</u> 3) (4) (5) (6) Reel)			
5.	Judication measuring method Inductance : LCR meter (HP 4285A or equivalent, 100KHz, 1V) Self-resonant : Impedance/Material (HP 4291A or equivalent) frequency Analyzer (HIOKI 3227 or equivalent) DC resistance : DC Ohmmeter (HIOKI 3227 or equivalent) Standard test conditions for electrical characteristics Unless otherwise specified, temperature is at 20 ± 15 and humidity is at 65 ± 20 %. Should any doubt arise about the test results, further test shall be conducted at a temperature 20 ± 2 and humidity 65 ± 5 %. For inductance our measured values shall be standard					
4.	Operating tem -25 to -	erature range 120 (Including self-heatir	ıg)			
5.	 Storage temperature range -40 to +85 (For products in unopened tape package, -5 to 40) 					
6.	Electrical char Refer to tab	cteristics e 1.				
7.	7. External dimensions and structural drawing Refer to Table 2.					
8.	8. Mechanical performance Refer to Table 3.					
9.	9. Environment test performance specifications Refer to Table 3.					
10.	Tape and Reel Refer to Tab	backaging dimensions e 4.				
11.	Packing form Refer to Tab	e 5.				
12.	Reflow profile Refer to Tab	: hart e 6.				

Table 1

ELECTRICAL CHARACTERISTICS

(2/12)

Ordering Code	Nominal	Inductance Tolerance [%]	D.C. Resistance ±20% [Ω]	Rated Current [mA]		Self-resonant Frequency
	[µH]			Saturation Current Idc1	Temperature Rise current Idc2	Min [MHz]
NRS6010T 1R5MMGF	1.5	±20	0.090	2400	1900	77
NRS6010T 2R2MMGF	2.2	±20	0.110	1900	1700	56
NRS6010T 3R3MMGF	3.3	±20	0.135	1600	1500	42
NRS6010T 4R7MMGF	4.7	±20	0.165	1300	1400	36
NRS6010T 6R8MMGF	6.8	±20	0.220	1200	1200	30
NRS6010T 100MMGF	10	±20	0.270	1000	1100	25
NRS6010T 220MMGF	22	±20	0.580	650	700	12

*) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%.

(at 20)

*) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40 $\,$.

(at 20)

*) The rated current is the DC current value that satisfies both of current saturation current value and temperature rise current value.

Table 2

EXTERNAL DIMENSIONS AND STRUCTURAL DRAWING

No.

(3/12)

1. External dimensions



): Reference value

(

Mark	Dimensions	
L	6.0 ± 0.2	
W	6.0 ± 0.2	
Н	1.0Max.	
е	1.35 ± 0.2	
е	0.3±0.2	
f	4.0 ± 0.2	(Unit: mm)
	Mark L W H e e f	MarkDimensionsL 6.0 ± 0.2 W 6.0 ± 0.2 H $1.0Max.$ e 1.35 ± 0.2 e 0.3 ± 0.2 f 4.0 ± 0.2

2. Structural drawing



Ferrite core Winding wire Over-coating resin Electrode Ni - Zn ferrite Polyurethane-copper wire Epoxy resin, containing External electrode (substrate) External electrode (base plating) External electrode (top surface solder coating)

Ag Ni - Sn Sn - Ag - Cu

Table 2

EXTERNAL DIMENSIONS AND STRUCTURAL DRAWING

<u>No.</u>

(4/12)

3. Core chipping The appearance standard of the chipping size in top side, of bottom side ferrite core is following dimension. W L 1.5mm Max. 1.5mmMax. W 4. Void appearance tolerance limit Size of voids occurring to coating resin is specified below. Width direction (dimension a) : Acceptable when a<=w/2 Nonconforming when a>w/2 Length direction (dimension b): Dimension b is not specified. b When total area of voids (including one exposing coil) occurring to each sides is not greater than 50% of coating resin area, that is acceptable. W 5. Electrode appearance criterion for exposed wire Cross section of wire joint part> <Appearance judgment> Good Upper part of wire is exposed.

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Less than 1/2 of joint side length.

Solder is shed by wire. It is not covered more than the half of the diameter with solder.

MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICEATIONS

Table 3

No.

(5/12)

		— () ()	
Test Item	Standard	lest method	
Inductance	Refer to Table 1.	LCR meter (HP4285A or equivalent)	
DC resistance	Refer to Table 1.	DC ohm meter (HIOKI3227 or equivalent)	
Rated current	Refer to Table 1.	Maximum DC value that does not cause inductance to decrease more than 30% with DC bias and does not cause temperature to increase by more than 40 .	
Self resonant frequency	Refer to Table 1.	Impedance/material analyzer (HP4291A or equivalent)	
Resistance to deflection	No damage.	The test samples shall be soldered to the test board by the reflow soldering conditions show in Table 6. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm.	
		R5 45 ± 2 45 ± 2 101 $R230$ 4.7 4.7 4.7 101 4.7 101	
		Land dimensions Test board size : 100 × 40 × 1.0 Test board material: glass epoxy-resin Solder group thickness: 0.1	
Adhesion of Terminal electrode	Shall not come off PC board	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6.	
		10 N, 5 s	
		Applied force: 10 N to X and Y directions. Duration: 5 s. Solder cream thickness: 0.15 mm (Refer to recommended Land Pattern Dimensions defined in "Precaution")	
Body strength	No damage.	Applied force: 10 N Duration: 10 s R0.5 mm	
	Inductance DC resistance Rated current Self resonant frequency Resistance to deflection Adhesion of Terminal electrode Body strength	Inductance Refer to Table 1. DC resistance Refer to Table 1. Rated current Refer to Table 1. Self resonant frequency Refer to Table 1. Resistance to deflection No damage. Adhesion of Terminal electrode Shall not come off PC board Body strength No damage.	

Table 3

MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICEATIONS No.

(6/12)

	Test Item	Standard	Test method		
	Resistance to vibration	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. Then it shall be submitted to below test conditions.			
			Frequency range 10Hz ~ 55 Hz		
			Total Amplitude 1.5 mm (May not exceed acceleration 196 m/S ²)		
			Sweeping Method 10Hz to 55Hz to 10 Hz for 1 min.		
			TimeFor 2 hours on each X, Y, and Z axis.		
	Resistance to soldering heat (Reflow)	L/L within ± 10 % No abnormality observed in appearance.	The test sample shall be exposed to reflow oven at 230 ± 5 for 40 seconds, with peak temperature at 260 ± 5 for 5 seconds, 2 times.		
			Test board thickness: 1.0 mm Test board material: glass epoxy-resin		
	Solderability	At least 90 % of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25 %.		
STS			Solder Temperature 245 ± 5		
ЦШ			Time 5 ± 1.0 s.		
⊢			Immersing Speed 25 mm/s		
Z W W Z O QTemperature temperature L/LL/L within ± 20 % No abnormality observed in appearance.Measurement temperature temperature With r rate s			Measurement of inductance shall be taken at temperature range within - 25 to + 85 . With reference to inductance value at + 20 , change rate shall be calculated.		
ENVI	Thermal shock	L/L within ± 10 % No abnormality observed in appearance.	The test samples shall be soldered to the test boar by the reflow soldering conditions shown in Table 6. The test samples shall be placed at specifie temperature for specified time by step 1 to step 4 a shown in below table in sequence. The temperature cycle shall be repeated 100 cycles		
			Step Temperature Time (min)		
			$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		
			2 Room Temp. 3 maximum		
			3 85±2 30±3 4 Room Temp 3 maximum		
	Low	L/L within ± 10 %	The test samples shall be soldered to the test board by		
temperature life testNo abnormality observed in appearance.the reflow soldering conditions s After that, the test samples s conditions as shown in below ta			the reflow soldering conditions shown in Table 6. After that, the test samples shall be placed at test conditions as shown in below table.		
			Temperature -40 ± 2		
			Time 500 + 24 h		

Table 3

MECHANICAL PERFORMANCE / ENVIRONMENTAL TEST PERFORMANCE SPECIFICEATIONS No.

(7/12)

	Test Item	Standard	Test method		
	Loading at high temperature life test	L/L within ± 10 % No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6. The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table		
			Temperature 85 ± 2		
			Applied current (Refer to Table 1)		
			Time 500 + 24 h		
VIRONMENT TESTS	Damp heat life test	L/L within ± 10 % No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6.The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.Temperature 60 ± 2 Humidity $90 \sim 95 \ \% RH$ Time $500 + 24 h$		
EN	Loading under damp heat life test	L/L within ± 10 % No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 6.The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.Temperature 60 ± 2 Humidity90 ~ 95 %RHApplied current (Refer to Table 1)Time $500 + 24 h$		

Standard	Liplace otherwise specified, the test samples are placed at room temperature
measuring condition	and humidity and measured within 48 hours after exposure to test conditions.

Table 4	<u>No.</u>
TAPE & REEL PACKAGING DIMENSIONS	(8/12)



Table 5

<u>No.</u>

PACKING FORM

(9/12)



Number of products 1 real	Maximum number in a carton		
Number of products free	Carton A	Carton B	
1000 pcs/1 reel	4000 pcs/4 reel	8000 pcs/8 reel	



Precautions

(11/12)

1 . Surface Mounting

- Mounting and soldering conditions should be checked beforehand.
- Applicable soldering process to this products is reflow soldering only.
- Recommended Land-Pattern :



(Unit: mm)

2. Handling

- Keep the products away from all magnets and magnetic objects.
- Be careful not to subject the products to excessive mechanical shocks.
- Please avoid applying impact to the products after mounted on pc board.
- Avoid ultrasonic cleaning.

3. Storage

To prevent deterioration of the solderability of terminal electrodes and/or the packing materials of the products, please store the products under following storage conditions.

- Ambient temperature range 0 to 40
 - 70 % RH maximum

Even under the ideal storage conditions, solderability of inductor's electrode deteriorates as time passes, so inductors should be used within 6 months after the delivery time.

4 . Regarding Regulations

Humidity

- Any Class or Class ozone-depleting substance (ODS) listed in the Clean Air Act in US for regulation is not included in the products or applied to the products at any stage of whose manufacturing processes.
- · Certain brominated flame retardants (PBBs, PBDEs) are not used at all.
- The products of this specifications are not subject to the Export Trade Control Order in Japan or the Export Administration Regulations in US.

5. RoHS compliance

This product conforms to "RoHS compliance".

6 . Production Sites and country of origin

TAIYO YUDEN (PHILIPPINES) INC.

	Precautions	<u>No.</u>		
		(12/12)		
 7 . Guarantee The guaranteed operating conditions of the products are in accordance with the conditions specified in this specifications. Please note that Taiyo Yuden Co., Ltd. takes no responsibility for any failure and/or abnormality which is caused by use under other than the aforesaid operating conditions. 				
	SPECIAL NOTICE			
 Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification. Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment. All electronic components in this specification are developed, designed and intended for use in general electronics equipment. (for AV, office automation, household, office supply, information service, telecommunication, (such as mobile phone or PC) etc.) Before incorporating the components or devices into any equipment in the field such as transportation, (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance. Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required. In addition, even electronic components or functional modules that are used for the general electronic 				
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